ASSOCIATION CONNECT ELECTRONICS INDUST	© Copyright 2005. IPC, I	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowelevel parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x Form Typ Distribute													
upplier Info	rmation														
Company name* Company unique ID			que ID	ie ID		Unique ID Authority					Response Date*				
nsemi						20						2025-05-10			
Contact Name Title - Contact				t	Phone - C			one - Contact*				Email - Contact*			
Product-Env-Stewards Product En				luct Enviro Compliance			NA				Prod	Product-Env-Stewards@onsemi.com			
Authorized Representative* Title - Repre				presentative		Pho	Phone - Representative*				Email	Email - Representative*			
Product-Env-Ste	wards]	Product Enviro Compliance			NA	NA				Prod	Product-Env-Stewards@onsemi.com			
Reque	ester Item Number	Mfr Item N	em Number Mfr Item Name				fective Date	Version	ersion Manufacturing Site		Site	Weight*		UOM	Unit Type
		NCV8160AMX290TB XDFN4 AD 2.9 G Noise and High		/ LDO 250 mA, Ultra-Lo PSRR	w 20	2025-05-10 THB			1.29		mg	Each			
Ianufacturin	g Proccess Information	l													
Termin	Terminal Plating / Grid Array Material		Terminal Base Alloy J-		J-STD-020 MSL Rating		Peak Process Body Tempera		mperatur	ure Max Time at Peak Tem		rature Number of Reflow Cycles		cles	
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)) (no CU	CU Alloy 1		1		260		С		sec	onds	3		
Comments							•			•	•		•		
vel 1 - maximun	n time at peak temperature d	uring solde	ering is 10-30) seconds											
	ation regarding material com														

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure	
Die	0.106	mg	Supplier	Silicon (Si)	7440-21-3		0.106	mg	
Die Attach Tape	0.01	mg	Supplier	Oxirane, (chloromethyl)-, homopolymer	24969-06-0		0.0015	mg	
			Supplier	2-Propenoic acid, 2-methyl-, polymer with butyl 2-propenoate and methyl 2-methyl-2-propenoate	25035-69-2		0.0015	mg	
			Supplier	Proprietary	Proprietary Data		0.001	mg	
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.0045	mg	
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.0015	mg	
Lead Frame	0.78	mg	Supplier	Magnesium (Mg)	7439-95-4		0.0012	mg	
			Supplier	Silicon (Si)	7440-21-3		0.0034	mg	
			В	Nickel (Ni)	7440-02-0		0.0196	mg	
			Supplier	Copper (Cu)	7440-50-8		0.7558	mg	
Mold Compound-Black	0.35	mg		Epoxy resin	proprietary data		0.0164	mg	
			Supplier	Phenol Resin	Proprietary Data		0.0164	mg	
			Supplier	Carbon Black (C)	1333-86-4		0.0004	mg	
			Supplier	Fused Silica (SiO2)	60676-86-0		0.3167	mg	
Plating	0.024	mg	Supplier	Palladium (Pd)	7440-05-3		0.0006	mg	
			В	Nickel (Ni)	7440-02-0		0.0211	mg	
			Supplier	Gold (Au)	7440-57-5		0.0023	mg	
Wire Bond - Au	0.02	mg	Supplier	Gold (Au)	7440-57-5		0.02	mg	